

# Semiconductor sensors development and applications WG-5.2

Status Report

FAPESP Thematic 2020/04867-2

May 25th 2023



# WG-5.2.1 & WG-5.2.2 : Recap

- WG-5.2.1 : ATLAS High Granularity Timing Detector (HGTD)
- WG-5.2.2 : Low Gain Avalanche Detectors (LGADs) for low energy applications

*Details on August [kick-off meeting](#)  
and More details on [March WG 5.2 Workshop](#)*

# WG 5.2.1: People and Action Items (Recap)

## 1. Current Team

- 1.1. M. Leite (Physicist)
- 1.2. G. Saito (MS,PhD)
- 1.3. R. Menegasso (TS)
- 1.4. M. Kuriyama (TS)
- 1.5. DD (Dedicated)
- 1.6. DD (Sharing with PA)
- 1.7. PD (Sharing with PA)
- 1.8. IC (TT-2 ?)
- 1.9. TT-4

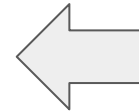
DD-4: *Ultra-fast semiconductor sensors and associated instrumentation for radiation detection*

## 1. Action items

- 1.1. Equipment availability (importation)
- 1.2. Preparing civil infrastructure for Lab
- 1.3. Lab installation
- 1.4. PD, DD, TT hiring
- 1.5. Start testing sensors
- 1.6. **Significant work to commission local infrastructure (EMU FAPESP)**
- 1.7. **Significant commitment of people on @CERN activities**

## 1. Deliverables

- 1.1. **LGAD Characterization Lab.**
- 1.2. **Characterization of LGAD sensors (on-going)**
- 1.3. **Performance studies on irradiated arrays (on-going)**
- 1.4. **PEB test stand system**
- 1.5. **Participation in HGTD assembly facility construction @ CERN (on-going)**
- 1.6. **Demonstrator construction @ CERN (on-going)**
- 1.7. **HGTD installation**
- 1.8. **HGTD commissioning**

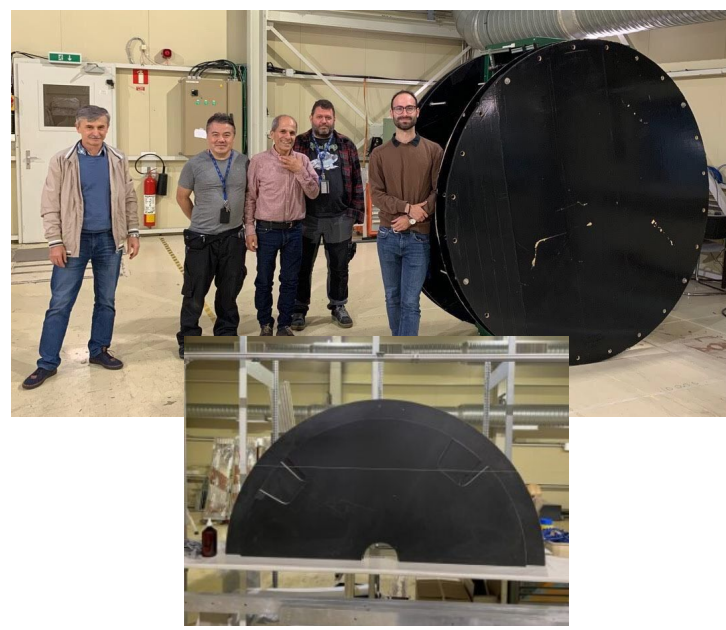


Almost zero float on these items !

# WG 5.2.1 : ATLAS HGTD - Infrastructure @CERN

On track (2023)

- **R. Menegasso & M. Kuriyama @ CERN (3 Months)**
  - Clean room and metrology setup for HGTD assembly @ B180
  - Demonstrator construction and thermal test system support
  -
- Next campaign July-October 2023

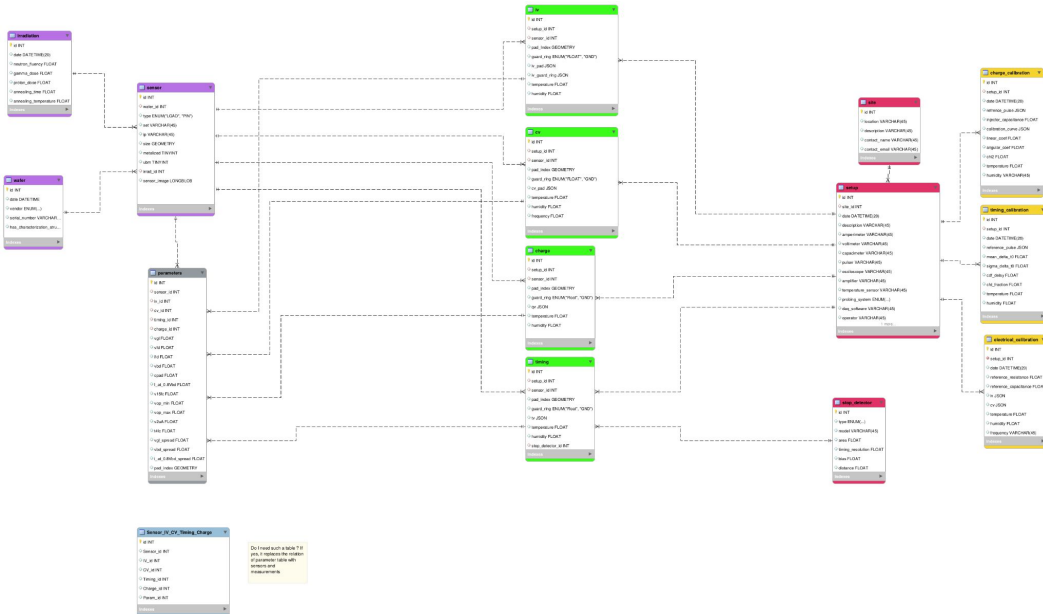


# WG 5.2.1 : ATLAS HGTD - Sensor test and Database

On Track

- M. Leite, G. Saito - collaboration in HGTD DB group
  - [Documentation \(Sphinx, gitlab pages\)](#)
  - Sensor database (MySQL)
  - Plot (Grafana)
- Concludes in 2023, updates after that

## DB Schema



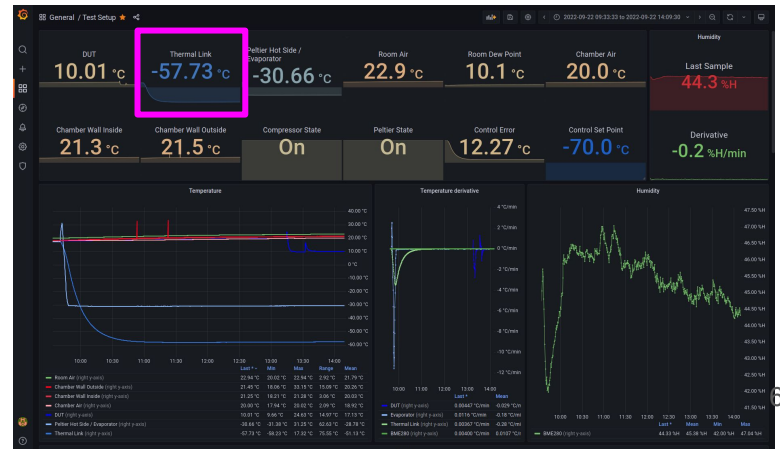
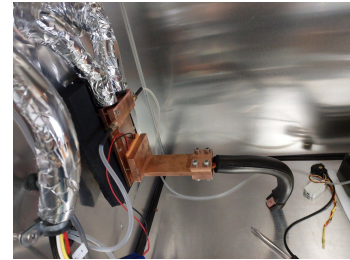
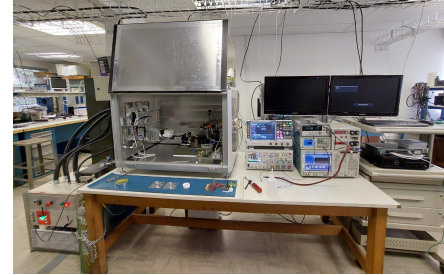
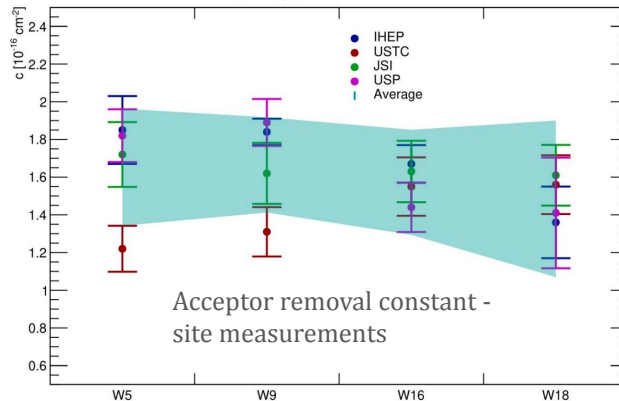
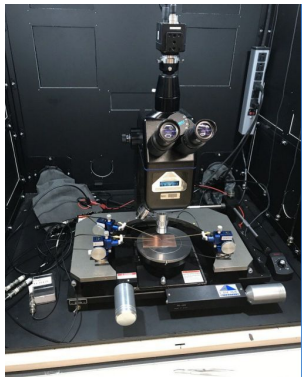
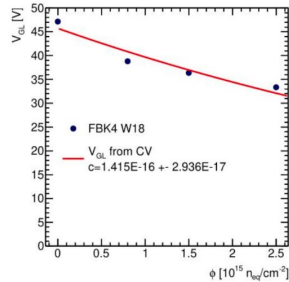
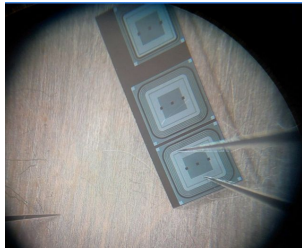
## DB Query and plot in Grafana

Example of a grafana dashboard showing information about sensors.

# WG 5.2.1 : ATLAS HGTD - Sensor tests and Database

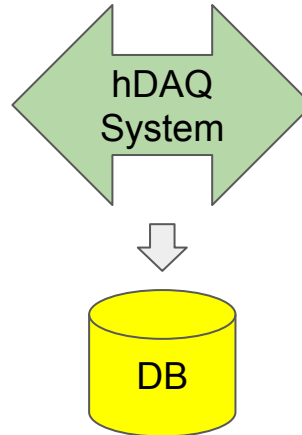
On Track

- M. Leite, G. Saito - ongoing sensor testing
  - Sensor tests at USP and FEI (M. Pavanello)
  - New laser system in 2023 ...
- Part of the commitments for HGTD (forever ...)



# WG 5.2.1 : ATLAS HGTD - Infraestructure @USP

- We need to be ready by ~~March 2023~~ as soon as possible
- Importation in several advanced stages by FAPESP and/or acquired in local distrib. (but support for other equip. across institutes)
- Bias tee, low noise connexion boxes and matrix switch being assembled



Watch

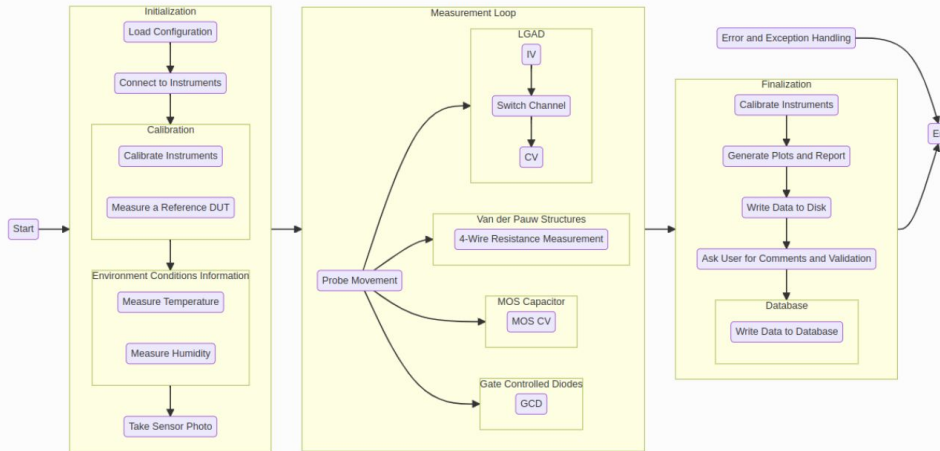
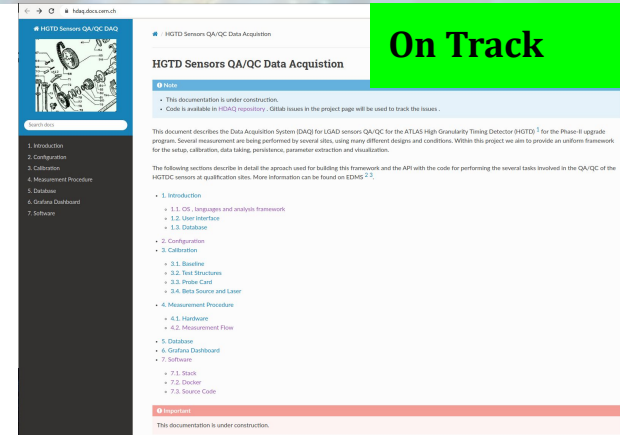


On Track



# WG 5.2.1 : ATLAS HGTD - hDAQ

- Integrated DAQ System for Sensor QC
- Unique system developed for CERN/IJS/IHEP/USP
- Sensor and control structures
- MySQL DB integration
- Part of the commitments for HGTD (forever ...)
- <https://hdaq.docs.cern.ch>
- [https://gitlab.cern.ch/ATLAS\\_USP/HGTD/Sensors/QAQC/HDAQ](https://gitlab.cern.ch/ATLAS_USP/HGTD/Sensors/QAQC/HDAQ)



## Development at São Paulo

Writing driver for our instruments

Done :

- Keithley Electrometer 6514
- Keithley Electrometer 6517B
- Keysight DMM 34461A
- R&S LCR HM8118

To do :

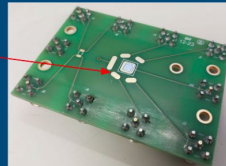
- Keithley SMU 2450
- R&S LCR LCX200
- Keysight Electrometer B2985B
- JSI switching matrix driver

## Reference Board

- PCB to wire bond a sensor or test structure die and SMD resistor/capacitor for calibration
- Handy to develop DAQ software
- Good to debug noise & connection (without Probe Station)

Reference Board:

HPK LGAD





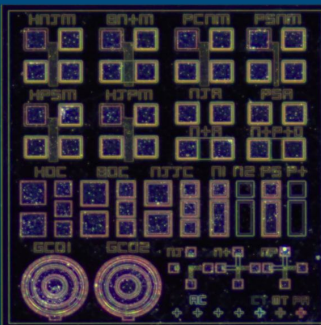
# WG 5.2.1 : ATLAS HGTD - Test structures

- First tests done at USP
- Done @FEI with M. Pavanello

## Test Structures

IHEP test structures:

- 3 Sheet Resistors
- 3 Contact Resistors
- 7 Capacitors
- 1 Diode
- 2 Gated Diodes
- 6 MOSFET



Not the production design

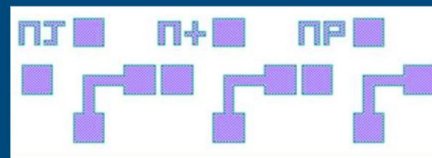
To get hands-on experience for the Sensors QC

## Contact Resistance

- NJ
  - NJTE contact resistor
- N+
  - N++ contact resistor
- NP
  - N++/P+ layer contact resistor

> First tried with B1500, but no reliable measurement

> Then used a DMM and LCR 4-wire Resistance



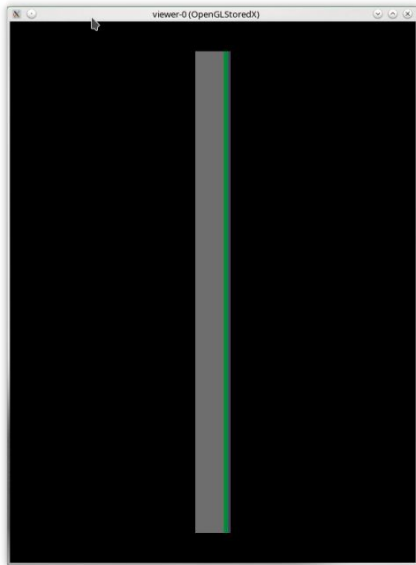
		NJ	N+	NP
DMM 34461	Die 1	378 k $\Omega$	13.0 $\Omega$	11.5 $\Omega$
	Die 2	386 k $\Omega$	13.6 $\Omega$	11.6 $\Omega$
	Die 3	374 k $\Omega$	12.9 $\Omega$	10.9 $\Omega$
LCR HM8118	Die 1	65 k $\Omega$	14.3 $\Omega$	12.8 $\Omega$
	Die 2	550 k $\Omega$	14.0 $\Omega$	12.6 $\Omega$
	Die 3	549 k $\Omega$	13.3 $\Omega$	11.5 $\Omega$

DMM 34461 Current Source: 1mA for 1k $\Omega$ ; 5 $\mu$ A for 1M $\Omega$   
LCR HM8118: 0.5V 20Hz

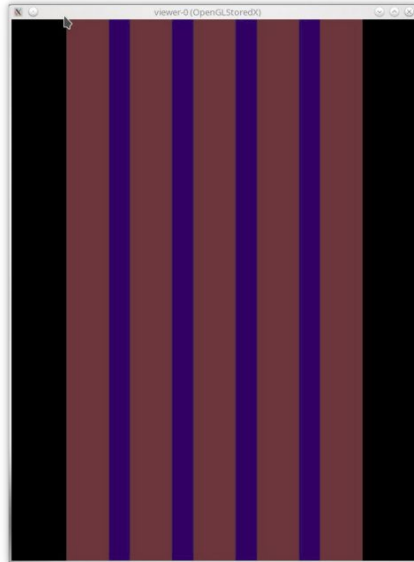
# WG 5.2.2 : Low Energy Applications - G4 Simulations

- First G4 simulation framework from M. Moralles for AC-LGADs
- More info on March WG 5.2 Workshop (<https://indico.cern.ch/event/1251642/contributions/>)

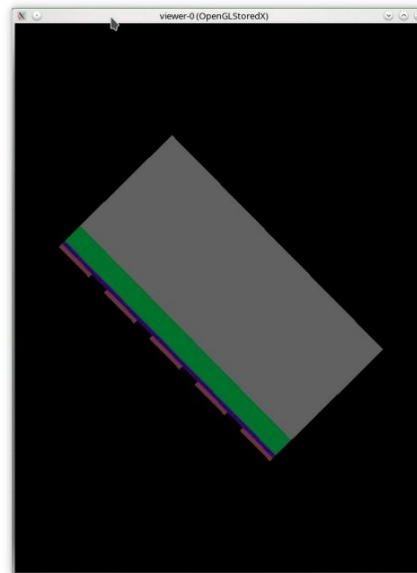
Detector - thickness view



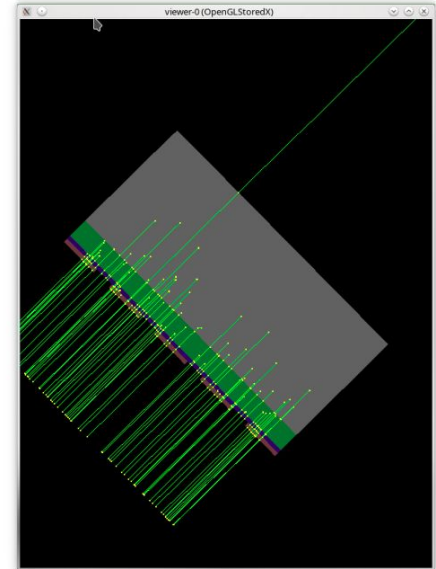
Detector - strips view



Detector - top view



Detector - top view with X-rays (8 keV)



# WG 5.2.2 : Low Energy Applications - TCAD Simulations

- TCAD AC-LGAD example from UCSC run by R. Buhler & R. Giacomini
- More info on March WG 5.2 Workshop (<https://indico.cern.ch/event/1251642/contributions/>)

## Simulação

Densidade de elétrons:

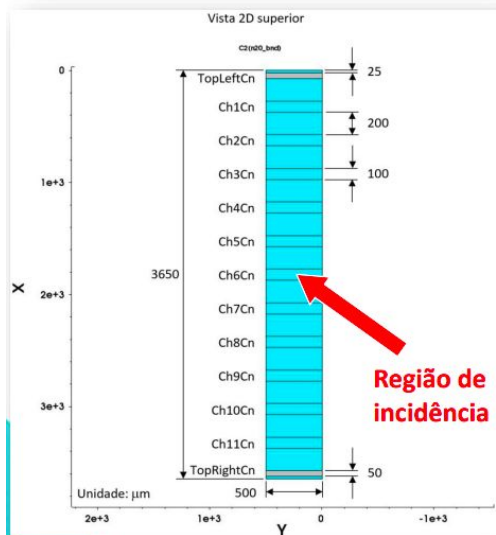
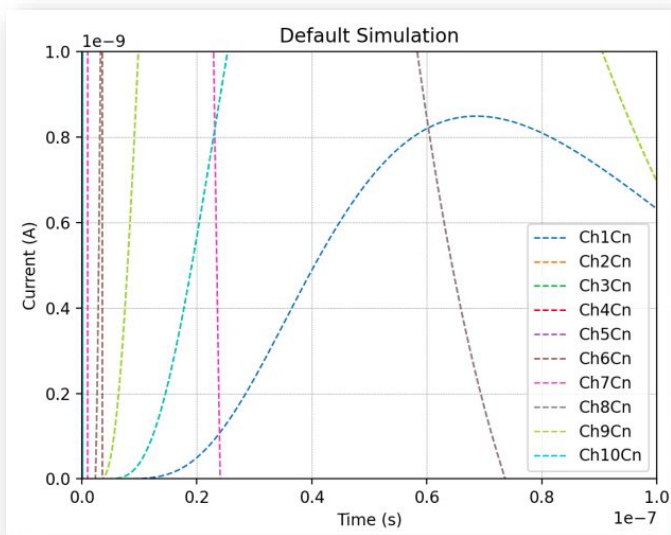


Gráfico da corrente ao longo do tempo e posição de cada eletrodo, alterando a escala da corrente



# WG 5.2.2 : Low Energy Applications - TCAD Simulations

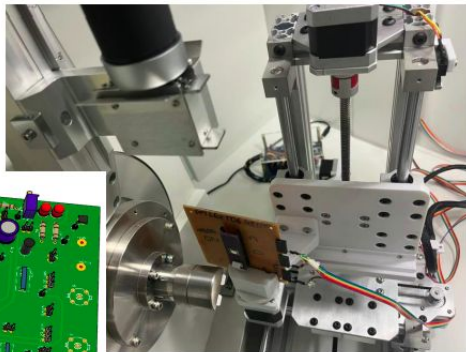
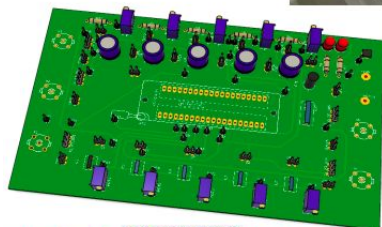
- LGAD TID tests (X-ray) @ FEI (M. Guazelli) bard with HPK 3.1 & 3.2 wire bonded
- More info on March WG 5.2 Workshop (<https://indico.cern.ch/event/1251642/contributions/>)

## EXEMPLO DE TESTE QUE ACABA DE SER PLANEJADO E PREPARADO NA FEI

### CI com 3 retangulares e 2 ELT

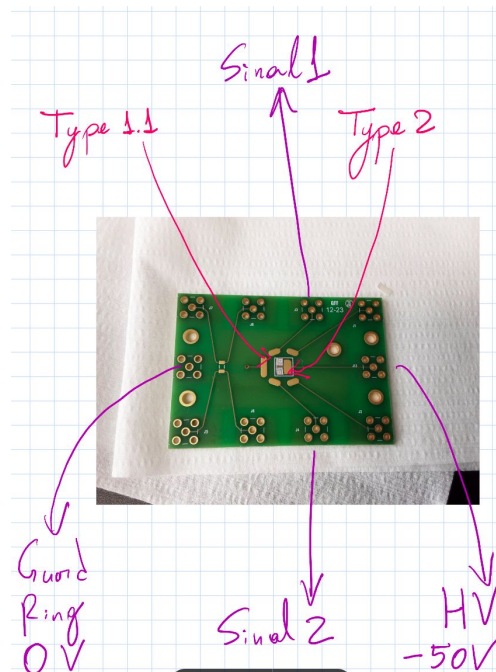
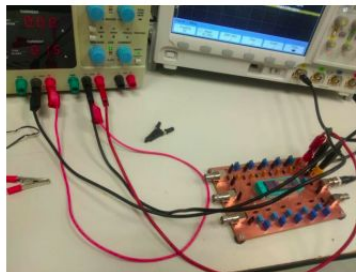
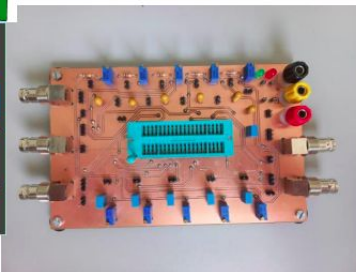
#### TID

Irradiado até 300 keV.  
Analisado antes,  
durante e após  
irradiação



#### SEE

Verificar sinal analógico do pico de corrente (SEE) em função do tempo. Número de SEE em função do tempo, para um determinado LET. Serão monitorados 1 Ret e 1 ELT ao mesmo tempo.



# WG 5.2.2 : SSRL LGAD and AC-LGAD Tests

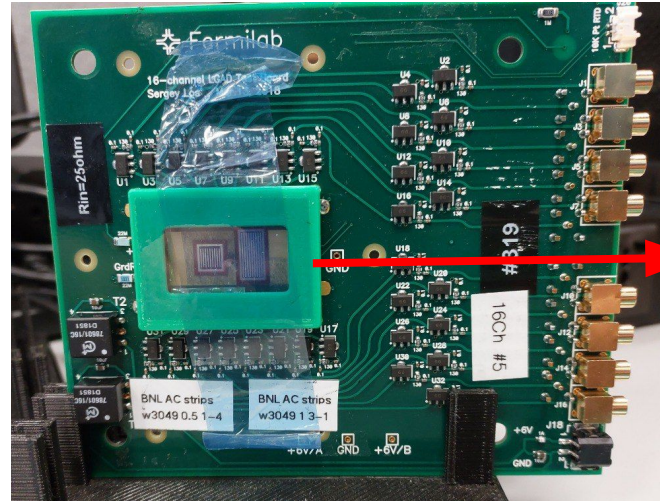
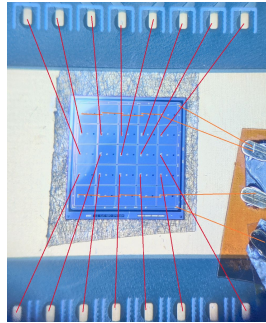
## LGADs/AC-LGADS for picosecond time-resolved X-ray testing

On Track

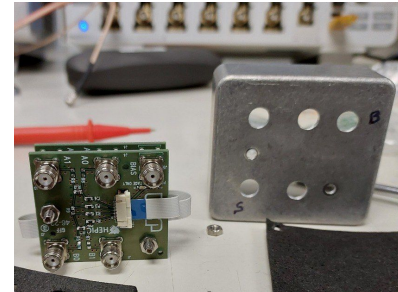
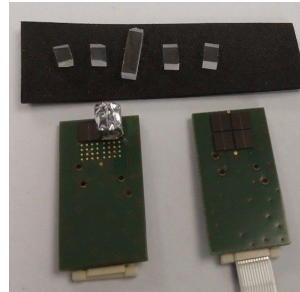
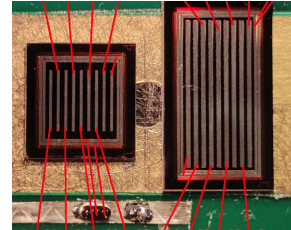
4. Radiation testing of *available* LGAD, AC-LGAD
  - 4.1. X-Ray testing
  - 4.2. Charged particle testing (electrons, protons, ions)
  - 4.3. Time Resolved X-Ray testing (**M. Leite & UCSC**)

Tested at Stanford SLAC SSRL test beam with UC Santa Cruz in November 2022

- Energies from 5keV to 53 keV (70 keV with harmonics)
- “Flat” beam (BL 11.2) : 12.6mm x 2.14mm
- Several intensities and bias voltages
- LGADs :
  - HPK 3.1 Single (1.3mm)
  - HPK 3.2 single (1.3mm)
  - HPK 3.2 5x5 (1.3mm)
  - BNL 20 $\mu$ m Single (1mm)
- AC-LGADs :
  - BNL strips



Strips  
AC-LGAD



Compton Box  
(SiPM + LYSO)

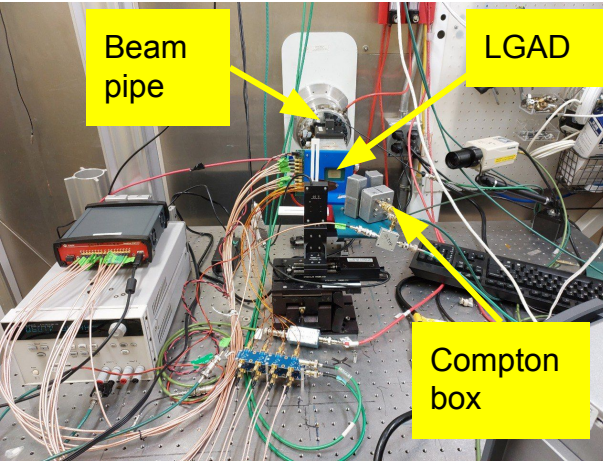
Long range and continuous effort - also discussion with Sirius detector group

# WG 5.2.2 : WBS and Deliverables

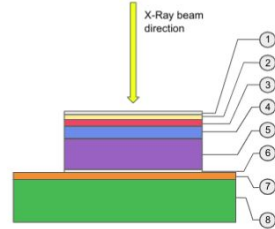
## Part-I - LGADS for picosecond time resolved X-ray testing

On Track

SSRL BL 11-2



- Significant amount of work since Dec. 2022
- Analysis almost completed, paper in preparation (JINST) to be submitted next month or so



LGAD layer	Thickness (µm)
1 Al cathode Contact	0.3
2 n++	1.0
3 gain (p+)	1.0
4 bulk active	45.0
5 p++ substrate	150.0
6 Al anode contact	0.3
PCB Base layer	
7 Copper Laminate	100
8 FR4	1600

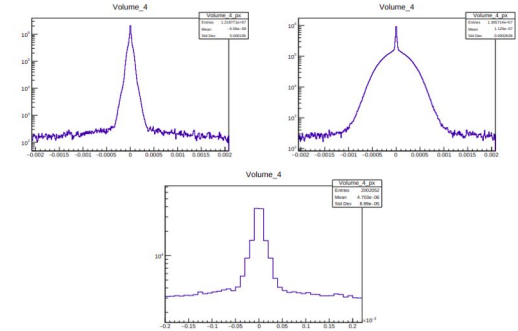
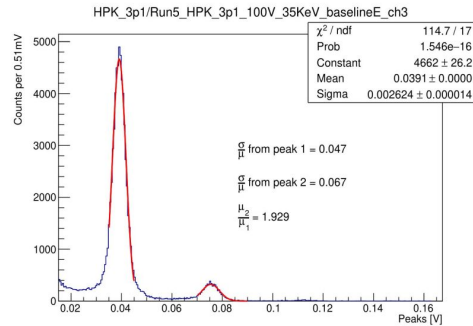


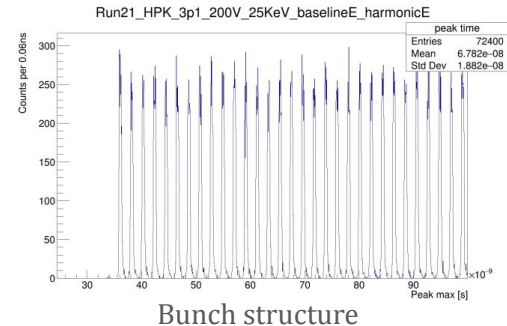
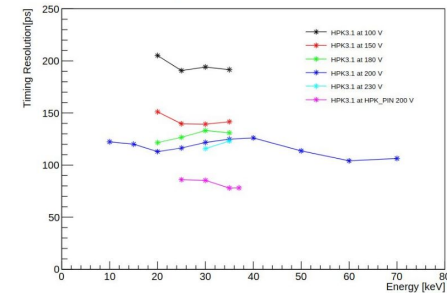
Figure 11: Simulation of primary charge transverse distribution (considering a point-like beam) in the LGAD BULK region for photons of 5(a), 10(b) and 30(c) keV

### Energy resolution



### Timing resolution

#### Timing Resolution CFD - HPK3.1



# WG 5.2.x : Deliverables

## Three papers about to be submitted

### 2 Performance of a front-end prototype ASIC for the ATLAS 3 High Granularity Timing Detector

4 E-mail: [makovec@cern.ch](mailto:makovec@cern.ch)

5 ABSTRACT: This paper presents the design and characterisation of a front-end prototype ASIC for  
6 the ATLAS High Granularity Timing Detector, which is planned for the High-Luminosity phase  
7 of the LHC. This prototype, called ALTIROC1, consists of a 5x5-pad matrix and contains the  
8 analog part of the single-channel readout (preamplifier, discriminator, two TDCs and SRAM).  
9 Two preamplifier architectures (transimpedance and voltage) were implemented and tested. The  
10 ASIC was characterised both alone and when connected to a 5x5-pad array of LGAD sensors. In  
11 calibration measurements, the ASIC operating alone was found to satisfy the technical requirements  
12 for the project, with similar performances for both preamplifier types. In particular, the jitter was  
13 found to be  $15 \pm 1$  ps (resp.  $35 \pm 1$  ps) for an injected charge of 10 fC (resp. 4 fC). A degradation  
14 in performance was observed when the ASIC was connected to the LGAD array. This is attributed  
15 to digital couplings at the entrance of the preamplifiers. When the ASIC is connected to the  
16 LGAD array, the lowest detectable charge increased from 1.5 fC to 3.4 fC. As a consequence,  
17 the jitter increased for an injected charge of 4 fC. Despite this increase, ALTIROC1 still satisfies  
18 the maximum jitter specification (below 65 ps) for the HGTD project. This coupling issue also  
19 affects the time-over-threshold measurements and the time-walk correction can only be performed  
20 with transimpedance preamplifiers. Beam test measurements with a pion beam at CERN were also  
21 undertaken to evaluate the performance of the module with LGAD pulses. The best time resolution  
22 obtained using only ALTIROC information was  $46.3 \pm 0.7$  ps for a restricted time-of-arrival range  
23 where the coupling issue is minimized. The residual time-walk contribution is equal to 23 ps and  
24 is the dominant electronic noise contribution to the time resolution at 15 fC.

### 2 Destructive breakdown studies of irradiated LGADs at 3 beam tests for the ATLAS HGTD

4 L. A. Beresford,<sup>a</sup> D. E. Boumediene,<sup>1b</sup> L. Castillo Garcia,<sup>1c</sup> L. D. Corpe,<sup>b</sup> M. J. Da Cunha  
5 Sargedas de Sousa,<sup>4d</sup> H. El Jarrari,<sup>e</sup> A. Eshkevarvakili,<sup>f</sup> C. Grieco<sup>2,g</sup>, S. Grinstein,<sup>e,m</sup>  
6 S. Guindon,<sup>f</sup> A. Howard,<sup>1g</sup> G. Kramberger,<sup>g</sup> A. Kurdish,<sup>h</sup> R. Mazzini,<sup>i</sup> M. Missio,<sup>j</sup>  
7 M. Morenas,<sup>k</sup> O. Perrin,<sup>l</sup> V. Raskina,<sup>l</sup> G. Saito,<sup>1m</sup> L. Serin,<sup>h</sup>

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9 <sup>b</sup>Laboratoire de Physique de Clermont-Ferrand (LPC), Université Clermont Auvergne, Campus Uni-  
10 versitaire des Cèzeaux, 4 Avenue Blaise Pascal, 63178 Aubière Cedex, France

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12 Carrer Can Magrans s/n, Edifici Cn, Campus UAB, E-08193 Bellaterra (Barcelona), Spain

13 <sup>d</sup>Department of Modern Physics and State Key Laboratory of Particle Detection and Electronics, University  
14 of Science and Technology of China (USTC), 96 Jinzhai Road Baohu District, Hefei, Anhui, 230026, China

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16 <sup>f</sup>Conseil Européen pour la Recherche Nucléaire (CERN), Esplanade des Particules 1, CH-1211 Meyrin,  
17 Switzerland

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19 <sup>h</sup>Laboratoire de Physique des 2 Infinis Irène Joliot Curie (IJCLab), 15 Rue Georges Clemenceau, 91400  
20 Orsay, France

21 <sup>i</sup>Academia Sinica, 128, Section 2, Academia Road, Nangang District, Taipei City, Taiwan 115

22 <sup>j</sup>Institute for Mathematics, Astrophysics and Particle Physics, Radboud University/Nikhef, Nijmegen, P.O.  
23 Box 9010, 6500 GL Nijmegen, Netherlands

24 <sup>k</sup>Omega, Ecole Polytechnique, Palaiseau, France

25 <sup>l</sup>Laboratoire de Physique Nucléaire et de Hautes Energies (LPNHE), Sorbonne Université, Université de  
26 Paris, CNRS/IN2P3, Paris, France

27 <sup>m</sup>Instituto de Física, Universidade de São Paulo, São Paulo, Brazil

28 <sup>n</sup>Institució Catalana de Recerca i Estudis Avançats (ICREA), Passeg de Lluís Companys, 23, 08010  
29 Barcelona, Spain

### X-ray detection with Low-Gain Avalanche Diodes

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M. Nizam<sup>1</sup> D. Yirda<sup>1</sup> N. Nagel<sup>1</sup> J. Ott<sup>1</sup> M. Leite<sup>2</sup> G. Saito<sup>2</sup>

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<sup>2</sup>Universidade de São Paulo, São Paulo (SP), Brazil

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ABSTRACT: The response of Low Gain Avalanche Diodes (LGADs), which are a type of thin  
silicon detector with internal gain, to X-rays of energies between 6-70 KeV was characterized at  
the SLAC light source (SSRL). The utilized beamline at SSRL was 11-2, with a nominal beam  
size of 3 cm x 0.5 cm, repetition rate of 500 MHz, and exceptionally monochromatic. LGADs of  
different thicknesses and gain layer configurations were read out using fast amplification boards and  
digitized with a fast oscilloscope. Standard PIN devices were characterized as well. The devices'  
energy resolution and time resolution as a function of X-ray energy were measured. The charge  
collection and multiplication mechanism were simulated using TCAD Sentaurus, and the results  
were compared with the collected data.

KEYWORDS: fast silicon sensors; charge multiplication; thin tracking sensors; X-rays; time resolution

# WG 5.2.1 & WG 5.2.2 : ACTION ITEMS FOR NEXT MONTHS

ATLAS  
HGTD

- Move ahead with USP infrastructure
  - Most critical item
  - Involves space, import and equipment purchase
  - Needs to prepare lab infrastructure while space discussion is on-going
- DAQ development and DB integration @ USP (in sync with CERN/IHEP/USTC/JSI)
- Infrastructure (baby demo and mockup) @ CERN
- Build the laser system with motorized stages + position measurement

on track

critical

new

New  
applications

- Validate first functional TCAD and Geant4 simulation
- Add Ad-hoc simulation code for multiplication mechanism
- Analyze data from TB @SLAC, resume discussion with Sirius (more people involved...)
- Understand irradiation needs and prepare infrastructure/tests at local facilities
- Explore/Converge designs for fabrication (WG 5.2.3 - see next presentation)

New  
involvements

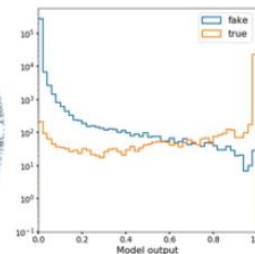
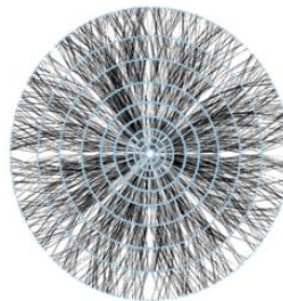
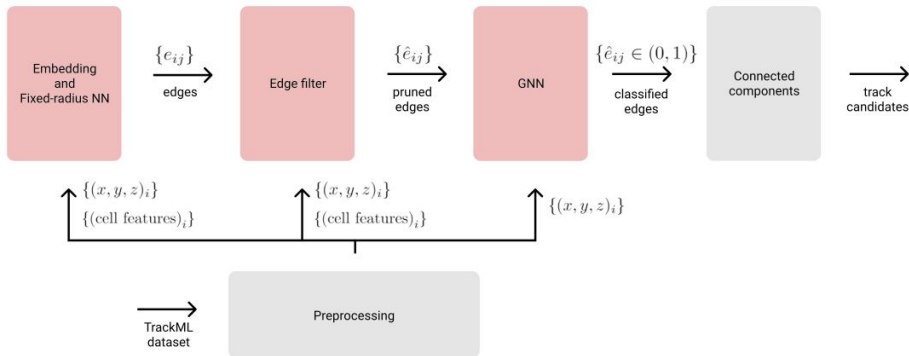
- **G. Saito** →DD (qualification tomorrow, "Ultra-Fast Silicon Detectors for Radiation Sensing"); R. Mansano (Poli) + M. Leite (IFUSP)
- **R. Estevam** →DD (Start next month : "*Métodos de aprendizado profundo e processamento de sinais aplicados à reconstrução de trajetórias em 4 dimensões para o HL-LHC*" ; V.H. Nascimento (Poli) + M.Leite (IFUSP)
- ECFA Detector Roadmap : DRD3 R&D on Solid State Detectors (on-going)



# WG 5.2.1 & WG 5.2.2 : ACTION ITEMS FOR NEXT MONTHS

## Graph based Neural Network approach for ATLAS HL-LHC (iTik+HGTD)

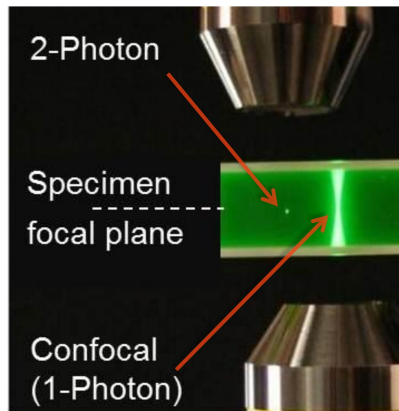
- Exa.trk: HEP advanced tracking algorithms at the Exascale



new

## Characterization of Semiconductor sensor using TCT and TPA Laser techniques

- Conventional TCT:
  - Localized generation of e-h pairs on X-Y
- Two-photon absorption TCT:
  - Localized generation of e-h pairs on X-Y-Z



Photography: Ciceron Yanez, University of Central Florida

## DRD-3 R&D on semiconductor sensors

- We are covering all ECFA DRDTs
- Additional WGs were added to cover simulations, facilities and dissemination corresponding to **General Strategic Recommendations (GSRs)** in the ECFA roadmap

